TLF-35A



Improved PTH and PIMD Performance

Benefits

- Improved PIMD with DK3.5
- Improved PTH Quality
- Stable at high frequency
- Stable at high temp.
- Low moisture absorption
- Excellent Peel Strength
- Excellent price/performance Ratio

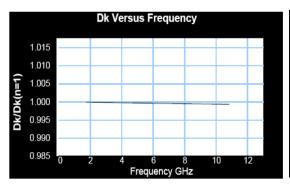
Applications

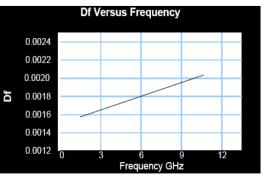
- Size effective Antenna
- Power Amplifiers
- LNA, Repeater PA
- Passive Components
- Filters / Couplers

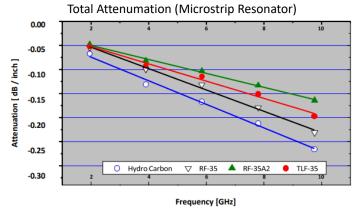


TLF-35A is an organic-ceramic laminate in Taconic's family of product. TLF-35A advanced is the best choice for low cost, high volume commercial microwave and radio frequency application. TLF-35A advanced has excellent peel strength for ½ ounce and 1 ounce copper and is designed to offer superior high frequency performance. Advanced TLF-35A laminates show similar electrical properties as TLF-35A but tighter DK tolerance.

TLF-35A advanced is designed to obtaining improved PIMD performances on size effective boards for antenna application. Most of sensitive PIMD required base material's Dielectric constant is around 3.0 whereas TLF-35A advanced laminates dielectric constant is 3.5 with similar PIMD levels.







Total Attenuation were measured with microstrip ring resonator.

Material under test were 20mil dielectric thickness and 1 oz. copper.



Properties	Conditions	Typical Value	Unit	Test Method	
Electrical Properties					
Dielectric Constant	@ 10 GHz	3.50 ± 0.05		IPC-TM 650 2.5.5.5.1 Mod	
Dissipation Factor	@ 10 GHz	0.0026		IPC-TM 650 2.5.5.5.1 Mod	
Surface Resistivity		3.0 x 10 ⁹	Mohms	IPC-TM 650 2.5.17.1	
Volume Resistivity		2.0 x 10 ⁸	Mohms/cm	IPC-TM 650 2.5.17.1	
Thermal Properties					
Thermal Conductivity		0.37	W/m/K	IPC-TM-650 2.4.50	
CTE (50 to 150 °C)	Х	9			
	Υ	12	ppm/°C	IPC-650 2.4.41	
	Z	80			
Mechanical Properties					
Peel Strength	1 oz. copper	1.8 (10)	N/mm (Lbs./linear in)	IPC-TM 650 2.4.8	
FI 10: 11	Lengthwise	90 (13,000)	N/mm² (psi)	IDO TAACEO O A A	
Flexural Strength	Crosswise 90 (13,000) N/m	N/mm² (psi)	IPC-TM 650 2.4.4		
Chemical / Physical Propert	ies				
Flammability			V-0	UL-94	
Water Absorption		0.03	%	IPC-TM 650 2.6.2.1	

Typical Thick	nesses ¹
Inches	mm
0.030	0.76
0.060	1.52

Typical Panel Sizes ²				
Inches	mm	Inches	mm	
12 x 18	305 x 457	18 x 24	457 x 610	
16 x 18	406 x 457	36 x 48	914 x 1,220	

Available Copper Cladding									
Designation	Weight	Copper T	hickness	Rms Tre	ated Side	Description			
CVH (CH)	½ oz./sq. ft.	~ .0007"	~18µm	19µin	$0.48 \mu \mathrm{m}$	Very low profile / Electrodeposited			
CV1 (C1)	1 oz./sq. ft.	~ .0014"	~ 35 <i>µ</i> m	25µin	0.64 <i>µ</i> m	Very low profile / Electrodeposited			
CLH	½ oz./sq. ft.	~ .0007"	~ 18µm	18µin	0.46µm	Reverse Treated / Electrodeposited			
CL1	1 oz./sq. ft.	~ .0014"	~ 35 <i>µ</i> m	16 µin	0.41µm	Reverse Treated / Electrodeposited			
C2	2 oz./sq. ft.	~ .0028"	~ 70µm	27 µin	0.69µm	Electrodeposited			
CVH (CH)	½ oz./sq. ft.	~ .0007"	~ 18µm	19µin	0.48µm	Very low profile / Electrodeposited			
CV1 (C1)	1 oz./sq. ft.	~ .0014"	~ 35µm	25 µin	0.64 <i>µ</i> m	Very low profile / Electrodeposited			

^{*} All test data provided are typical values and not intended to be specification values. For review of critical specification tolerances, please contact a company representative directly.



^{*} TLF-35A can be manufactured in increments of 0.030"(0.76mm).

^{*} Standard panel size is 18" x 24" (457 mm x 610 mm).

^{*} Please contact AGC for availability of additional thicknesses, other sizes & any other type of cladding.